

NOTES.

- 1. APPLICABLE HOUSING : 51110-***1 ; 51110-***5

GOLD FLASH 0.05-0.125 μ M	50394-8400	50394-8054
0.38 Pd/Ni w/ GOLD FLASH	50394-8300	50394-8053
0.76	50394-8200	50394-8052
0.38	50394-8100	50394-8051
Au. PLATE THICK. (μ m MIN.)	FORM: LOOSE	FORM: CHAIN
ENG.No.		

B	VOID PART NO. PER ECN S2004-0719	---	ANG LING	040223	MATERIAL : PHOSPHOR BRONZE (THK=0.152)	MOLEX SINGAPORE PTE LTD SHEET 1 OF 1
A2	ADD GOLD FLASH AS PER ECN*S2003-0030	---	NASH LING	02/07/12		
A1	ADD 0.38 Pd/Ni WITH GOLD FLASH AS PER PDR*98-01- 0267 (ECN*S1998-0364)	---	SEE LING	980312	FINISH : SEE NOTES	GENERAL TOLERANCES ± 0.20/.008
A	REL AS PER ECN*	S40519	SO EDP	940420		DRAWN BY S.O. 940420
LTR	REVISION RECORD	ECN	DR CHK	DATE	APPR'D BY ROY 940428	SCALE 15:1
REVISE ONLY ON CAD SYSTEM					TITLE : 2.0mm GRID W TO B CONN. CRIMP TERMINAL	

DWG. NO. SD-50394-8051

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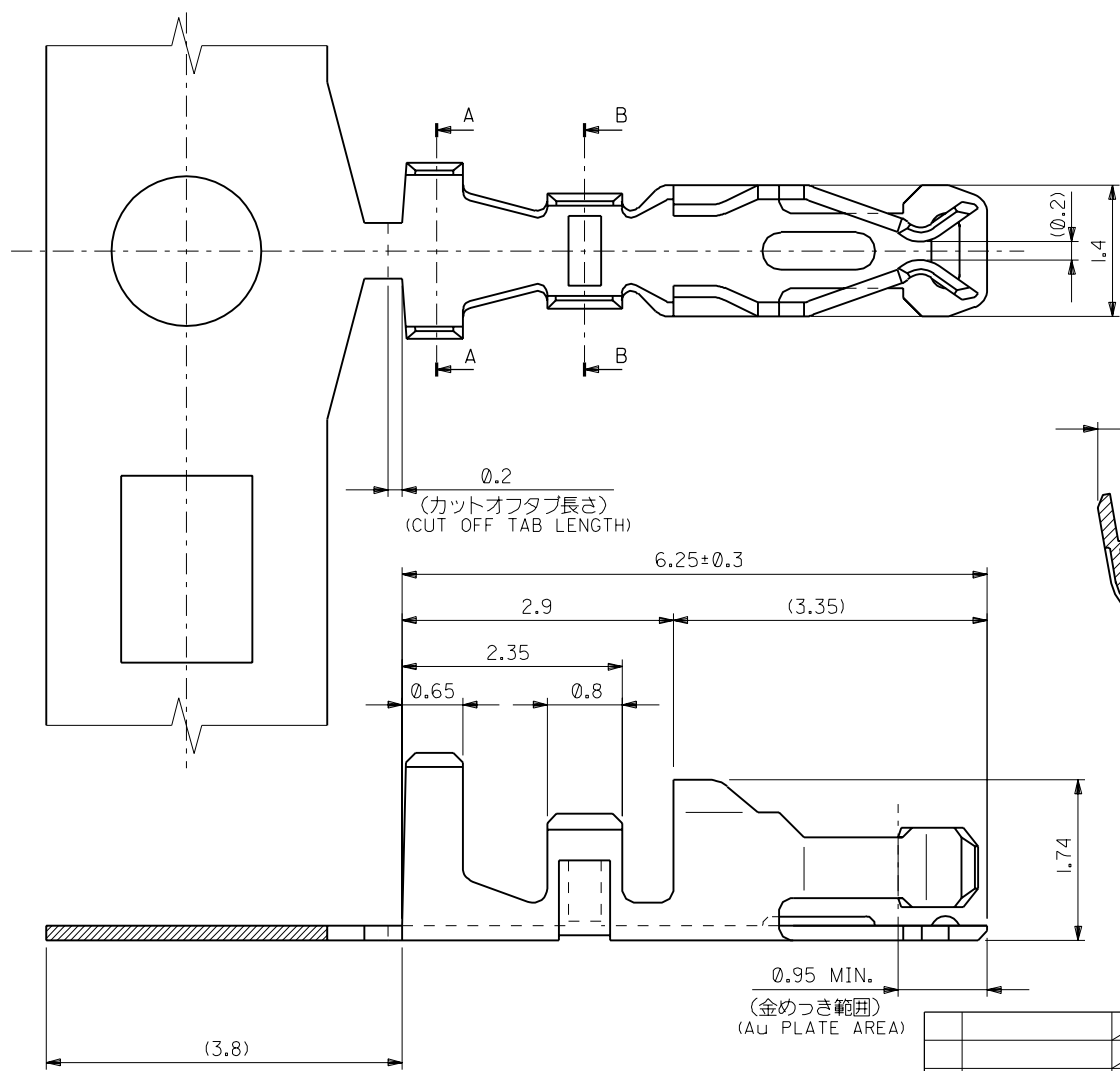
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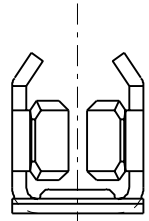
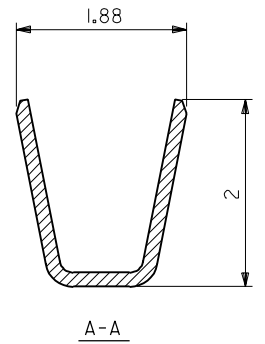
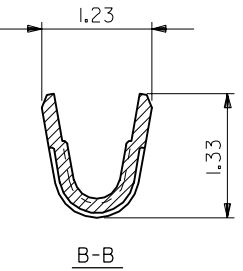
A

:MM DIMENSIONS IN METRIC DO NOT SCALE DRAWING

8 7 6 5 4 3 2 1



- 注)
NOTES.
1. 適合ハウジング: 5110-***1
APPLICABLE HOUSING : 5110-***1
 2. めっき仕様
PLATING SPEC
ニッケル下地金のつき (0.38µmMIN.) 仕上げ
Au (0.38µm MIN.) OVER NI PLATE



連鎖状 CHAIN	50394-8051
端子形状 TERM. FORM	製品番号 ENG.NO.

材料 MATERIAL 磷青銅 (板厚: 0.152) PHOS.-BRON. (t=0.152)	molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社
仕上げ FINISH 注)参照 SEE NOTES	
適用電線範囲 WIRE RANGE #24 ~ #30	REVISE ONLY ON CAD SYSTEM
被覆外径 INS. RANGE φ1.4 MAX.	TITLE 名称 2.0mm GRID W TO B CONN. CRIMP TERMINAL
DRAWN BY '93/05/08 CHK'D BY	DWG. NO. SD-50394-8051
新規作成 RELEASED (T30209)	REV 0
変更内容 REVISION RECORD	
記号 LTR	
DR. Y.1 CHK. DATE	
日付 DATE	
APP'D BY SCALE 20-1	

角度 ANGLE	+3°
30以上 OVER	+0.3
10以上 30未満 OVER UNDER	+0.25
10未満 UNDER	+0.2
一般公差 GENERAL TOLERANCES	

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